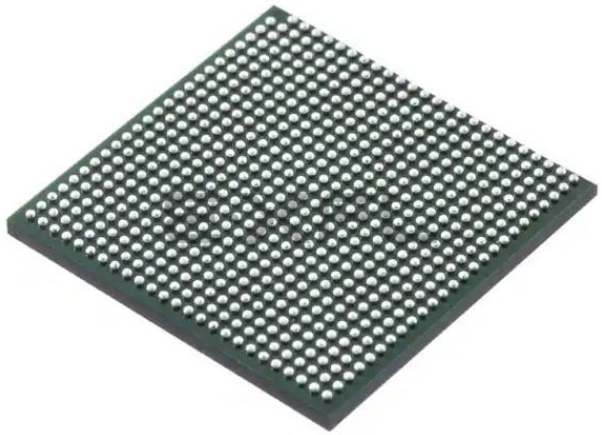

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	ARM® Cortex®-A9
Number of Cores/Bus Width	2 Core, 32-Bit
Speed	852MHz
Co-Processors/DSP	Multimedia; NEON™ SIMD
RAM Controllers	LPDDR2, DDR3L, DDR3
Graphics Acceleration	Yes
Display & Interface Controllers	HDMI, Keypad, LCD, LVDS, MIPI/DSI, Parallel
Ethernet	10/100/1000Mbps (1)
SATA	SATA 3Gbps (1)
USB	USB 2.0 + PHY (3), USB 2.0 OTG + PHY (1)
Voltage - I/O	1.8V, 2.5V, 2.8V, 3.3V
Operating Temperature	-40°C ~ 125°C (TJ)
Security Features	ARM TZ, A-HAB, CAAM, CSU, SJC, SNVS
Package / Case	624-FBGA, FCBGA
Supplier Device Package	624-FCBGA (21x21)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mcimx6dp6avt8ab

Table 2. i.MX 6DualPlus/6QuadPlus Modules List (continued)

Block Mnemonic	Block Name	Subsystem	Brief Description
GPU3Dv6	Graphics Processing Unit-3D, ver. 6	Multimedia Peripherals	The GPU2Dv6 provides hardware acceleration for 3D graphics algorithms with sufficient processor power to run desktop quality interactive graphics applications on displays up to HD1080 resolution. The GPU3D provides OpenGL ES 3.0, including extensions, OpenGL ES 2.0, OpenGL ES 1.1, and OpenVG 1.1
GPUVGv2	Vector Graphics Processing Unit, ver. 2	Multimedia Peripherals	OpenVG graphics accelerator provides OpenVG 1.1 support as well as other accelerations, including Real-time hardware curve tesselation of lines, quadratic and cubic Bezier curves, 16x Line Anti-aliasing, and various Vector Drawing functions.
HDMI Tx	HDMI Tx interface	Multimedia Peripherals	The HDMI module provides HDMI standard interface port to an HDMI 1.4 compliant display.
HSI	MIPI HSI interface	Connectivity Peripherals	The MIPI HSI provides a standard MIPI interface to the applications processor.
I^2C-1 I^2C-2 I^2C-3	I^2C Interface	Connectivity Peripherals	I^2C provide serial interface for external devices. Data rates of up to 400 kbps are supported.
IOMUXC	IOMUX Control	System Control Peripherals	This module enables flexible IO multiplexing. Each IO pad has default and several alternate functions. The alternate functions are software configurable.
IPUv3H-1 IPUv3H-2	Image Processing Unit, ver. 3H	Multimedia Peripherals	IPUv3H enables connectivity to displays and video sources, relevant processing and synchronization and control capabilities, allowing autonomous operation. The IPUv3H supports concurrent output to two display ports and concurrent input from two camera ports, through the following interfaces: • Parallel Interfaces for both display and camera • Single/dual channel LVDS display interface • HDMI transmitter • MIPI/DSI transmitter • MIPI/CSI-2 receiver The processing includes: • Image conversions: resizing, rotation, inversion, and color space conversion • A high-quality de-interlacing filter • Video/graphics combining • Image enhancement: color adjustment and gamut mapping, gamma correction, and contrast enhancement • Support for display backlight reduction
KPP	Key Pad Port	Connectivity Peripherals	KPP Supports 8 x 8 external key pad matrix. KPP features are: • Open drain design • Glitch suppression circuit design • Multiple keys detection • Standby key press detection

Table 2. i.MX 6DualPlus/6QuadPlus Modules List (continued)

Block Mnemonic	Block Name	Subsystem	Brief Description
WDOG-2 (TZ)	Watchdog (TrustZone)	Timer Peripherals	The TrustZone Watchdog (TZ WDOG) timer module protects against TrustZone starvation by providing a method of escaping normal mode and forcing a switch to the TZ mode. TZ starvation is a situation where the normal OS prevents switching to the TZ mode. Such a situation is undesirable as it can compromise the system's security. Once the TZ WDOG module is activated, it must be serviced by TZ software on a periodic basis. If servicing does not take place, the timer times out. Upon a time-out, the TZ WDOG asserts a TZ mapped interrupt that forces switching to the TZ mode. If it is still not served, the TZ WDOG asserts a security violation signal to the CSU. The TZ WDOG module cannot be programmed or deactivated by a normal mode Software.
EIM	NOR-Flash /PSRAM interface	Connectivity Peripherals	The EIM NOR-FLASH / PSRAM provides: • Support 16-bit (in muxed IO mode only) PSRAM memories (sync and async operating modes), at slow frequency • Support 16-bit (in muxed IO mode only) NOR-Flash memories, at slow frequency • Multiple chip selects
XTALOSC	Crystal Oscillator interface	—	The XTALOSC module enables connectivity to external crystal oscillator device. In a typical application use-case, it is used for 24 MHz oscillator.

3.1 Special Signal Considerations

The package contact assignments can be found in Section 6, "Package Information and Contact Assignments." Signal descriptions are defined in the i.MX 6DualPlus/6QuadPlus reference manual (IMX6DQPRM). Special signal consideration information is contained in the Hardware Development Guide for i.MX 6Quad, 6Dual, 6DualLite, 6Solo Families of Applications Processors (IMX6DQ6SDLHDG).

3.2 Recommended Connections for Unused Analog Interfaces

The recommended connections for unused analog interfaces can be found in the section, "Unused analog interfaces," of the Hardware Development Guide for i.MX 6Quad, 6Dual, 6DualLite, 6Solo Families of Applications Processors (IMX6DQ6SDLHDG).

CAUTION

The internal RTC oscillator does not provide an accurate frequency and is affected by process, voltage, and temperature variations. NXP strongly recommends using an external crystal as the RTC_XTALI reference. If the internal oscillator is used instead, careful consideration must be given to the timing implications on all of the SoC modules dependent on this clock.

The OSC32k runs from VDD_SNVS_CAP, which comes from the VDD_HIGH_IN/VDD_SNVS_IN power mux.

Table 20. OSC32K Main Characteristics

Parameter	Min	Typ	Max	Comments
Fosc	—	32.768 kHz	—	This frequency is nominal and determined mainly by the crystal selected. 32.0 K would work as well.
Current consumption	—	4 μA	—	The typical value shown is only for the oscillator, driven by an external crystal. If the internal ring oscillator is used instead of an external crystal, then approximately 25 μA must be added to this value.
Bias resistor	—	14 MΩ	—	This the integrated bias resistor that sets the amplifier into a high gain state. Any leakage through the ESD network, external board leakage, or even a scope probe that is significant relative to this value will debias the amplifier. The debiasing will result in low gain, and will impact the circuit's ability to start up and maintain oscillations.
Target Crystal Properties				
Cload	—	10 pF	—	Usually crystals can be purchased tuned for different Cloads. This Cload value is typically 1/2 of the capacitances realized on the PCB on either side of the quartz. A higher Cload will decrease oscillation margin, but increases current oscillating through the crystal.
ESR	—	50 kΩ	100 kΩ	Equivalent series resistance of the crystal. Choosing a crystal with a higher value will decrease the oscillating margin.

4.6 I/O DC Parameters

This section includes the DC parameters of the following I/O types:

- General Purpose I/O (GPIO)
- Double Data Rate I/O (DDR) for LPDDR2 and DDR3/DDR3L modes
- LVDS I/O
- MLB I/O

NOTE

The term ‘OVDD’ in this section refers to the associated supply rail of an input or output.

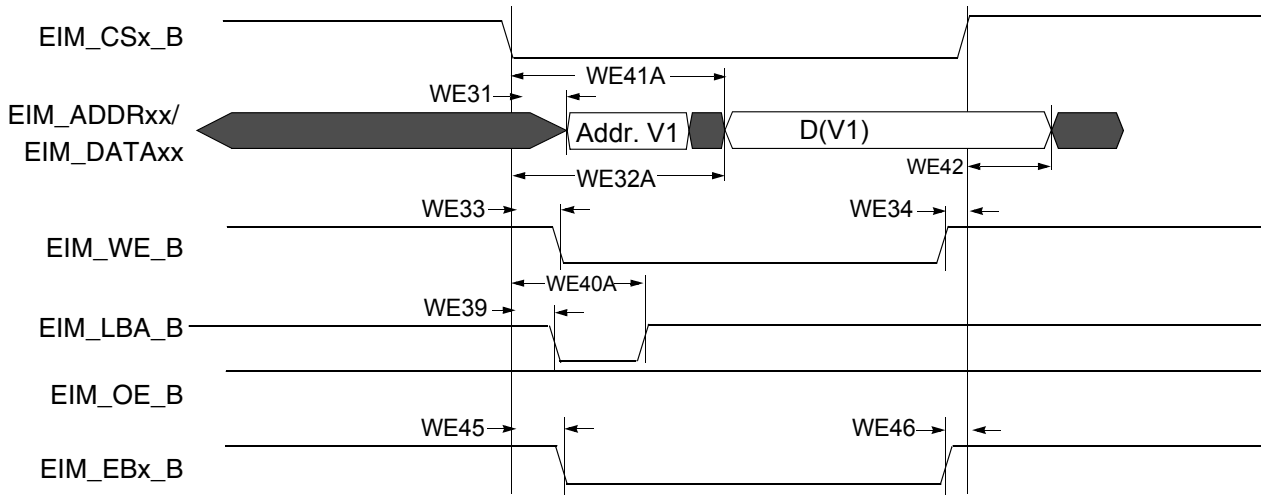


Figure 21. Asynchronous A/D Muxed Write Access

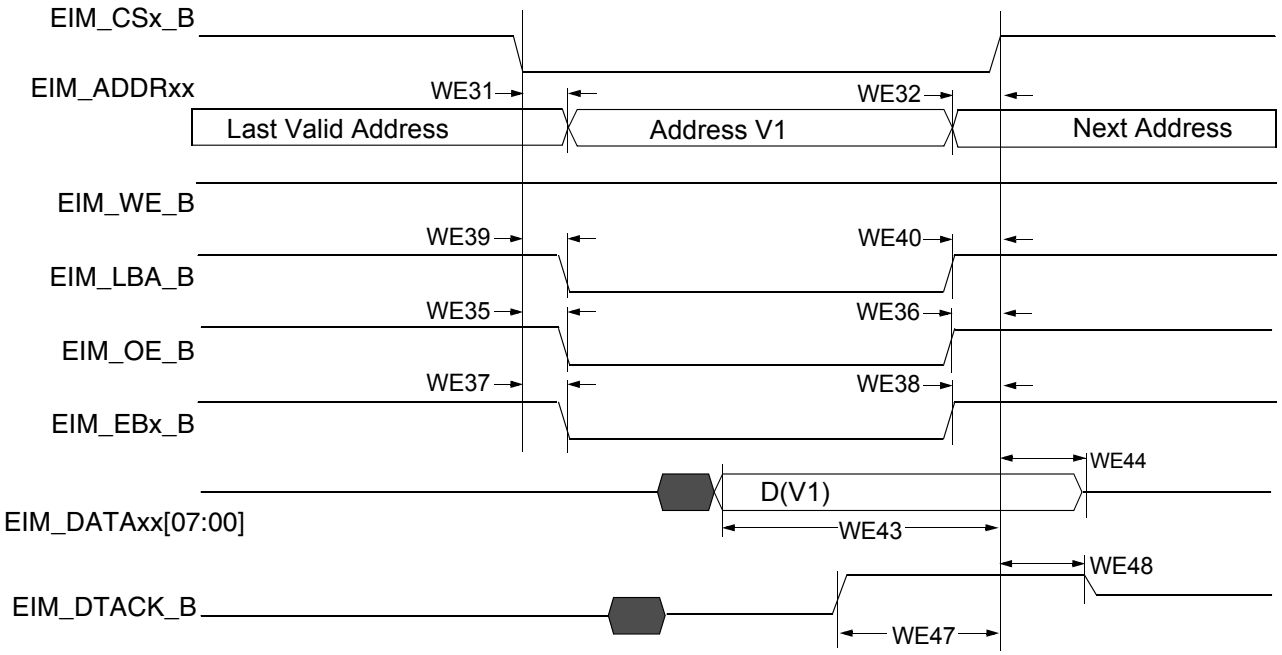


Figure 22. DTACK Mode Read Access (DAP=0)

4.11.2 Source Synchronous Mode AC Timing (ONFI 2.x Compatible)

Figure 29 shows the write and read timing of Source Synchronous mode.

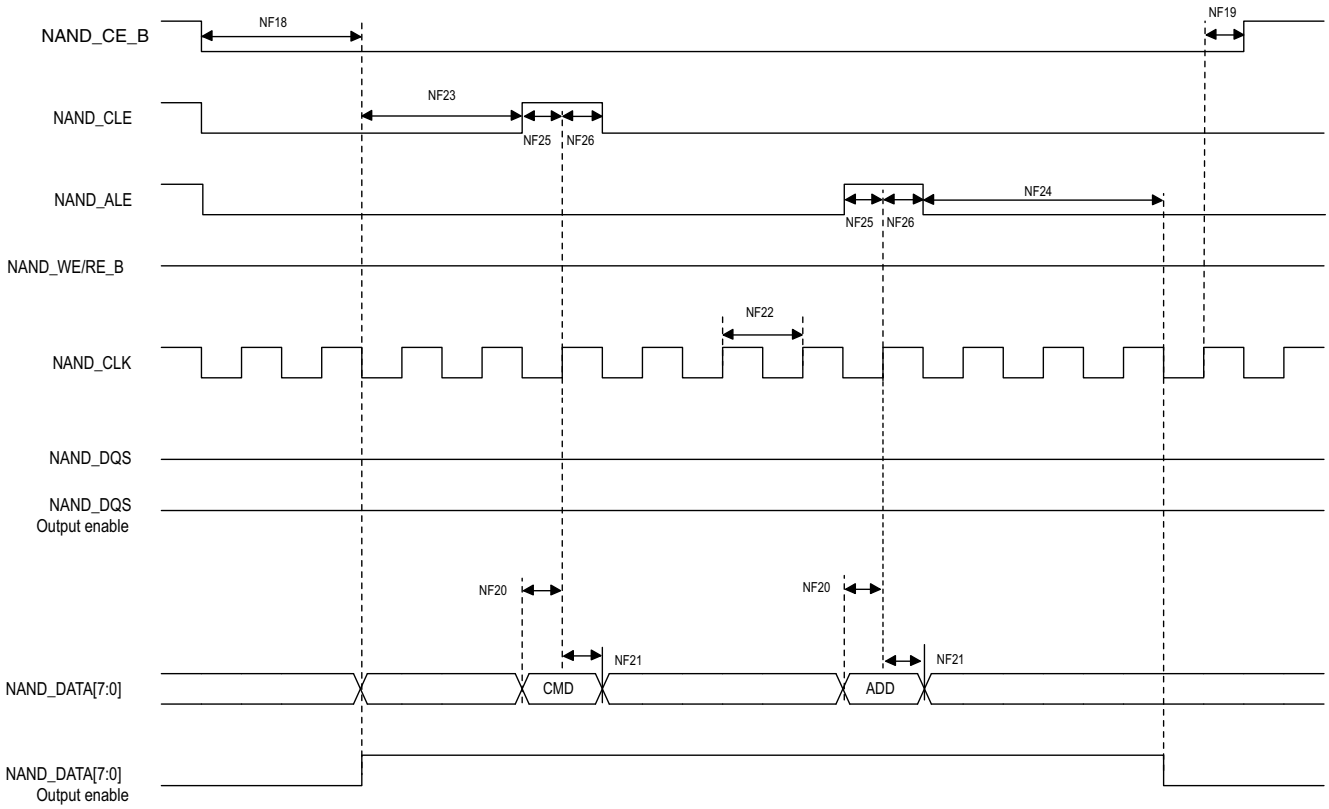


Figure 29. Source Synchronous Mode Command and Address Timing Diagram

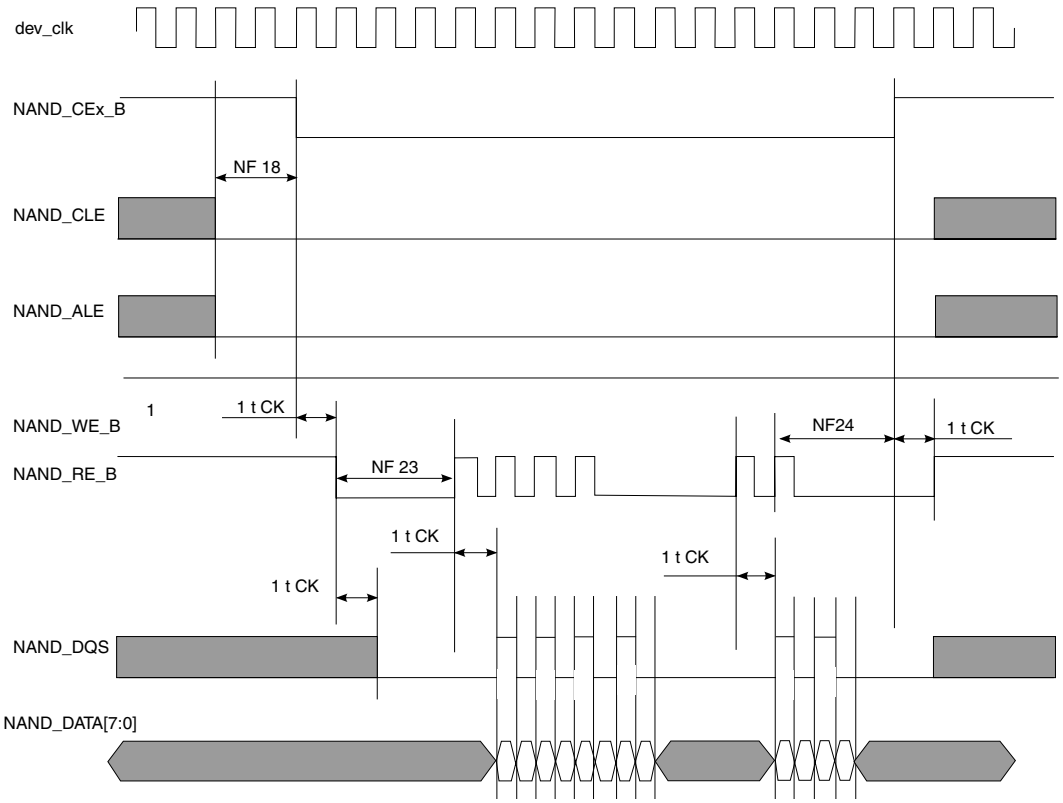


Figure 34. Samsung Toggle Mode Data Read Timing

Table 46. Samsung Toggle Mode Timing Parameters[1]

ID	Parameter	Symbol	Timing T = GPMI Clock Cycle		Unit
			Min	Max	
NF1	NAND_CLE setup time	tCLS	(AS + DS) × T - 0.12 [see 2,3]		—
NF2	NAND_CLE hold time	tCLH	DH × T - 0.72 [see 2]		—
NF3	NAND_CEx_B setup time	tCS	(AS + DS) × T - 0.58 [see 3,2]		—
NF4	NAND_CEx_B hold time	tCH	DH × T - 1 [see 2]		—
NF5	NAND_WE_B pulse width	tWP	DS × T [see 2]		—
NF6	NAND_ALE setup time	tALS	(AS + DS) × T - 0.49 [see 3,2]		—
NF7	NAND_ALE hold time	tALH	DH × T - 0.42 [see 2]		—
NF8	Command/address NAND_DATAxx setup time	tCAS	DS × T - 0.26 [see 2]		—
NF9	Command/address NAND_DATAxx hold time	tCAH	DH × T - 1.37 [see 2]		—
NF18	NAND_CEx_B access time	tCE	CE_DELAY × T [see 4,2]	—	ns
NF22	clock period	tCK	—	—	ns
NF23	preamble delay	tPRE	PRE_DELAY × T [see 5,2]	—	ns
NF24	postamble delay	tPOST	POST_DELAY × T +0.43 [see 2]	—	ns

4.12.5.1.2 MII Transmit Signal Timing (ENET_TX_DATA3,2,1,0, ENET_TX_EN, ENET_TX_ER, and ENET_TX_CLK)

The transmitter functions correctly up to an ENET_TX_CLK maximum frequency of 25 MHz + 1%. There is no minimum frequency requirement. Additionally, the processor clock frequency must exceed twice the ENET_TX_CLK frequency.

Figure 43 shows MII transmit signal timings. Table 54 describes the timing parameters (M5–M8) shown in the figure.

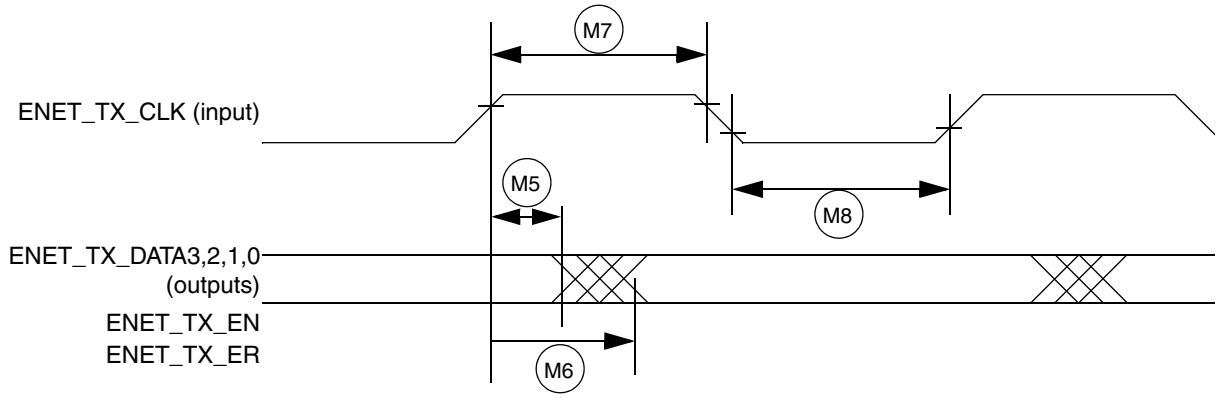


Figure 43. MII Transmit Signal Timing Diagram

Table 54. MII Transmit Signal Timing

ID	Characteristic[1]	Min	Max	Unit
M5	ENET_TX_CLK to ENET_TX_DATA3,2,1,0, ENET_TX_EN, ENET_TX_ER invalid	5	—	ns
M6	ENET_TX_CLK to ENET_TX_DATA3,2,1,0, ENET_TX_EN, ENET_TX_ER valid	—	20	ns
M7	ENET_TX_CLK pulse width high	35%	65%	ENET_TX_CLK period
M8	ENET_TX_CLK pulse width low	35%	65%	ENET_TX_CLK period

[1] ENET_TX_EN, ENET_TX_CLK, and ENET0_TXD0 have the same timing in 10-Mbps 7-wire interface mode.

4.12.5.1.3 MII Asynchronous Inputs Signal Timing (ENET_CRS and ENET_COL)

Figure 44 shows MII asynchronous input timings. Table 55 describes the timing parameter (M9) shown in the figure.

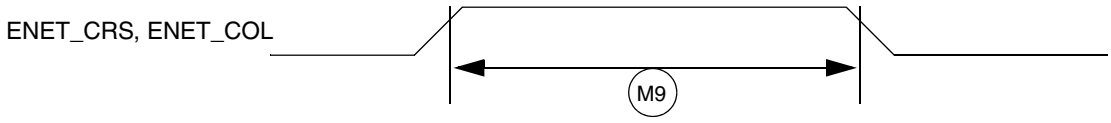


Figure 44. MII Async Inputs Timing Diagram

4.12.10.1 IPU Sensor Interface Signal Mapping

The IPU supports a number of sensor input formats. Table 62 defines the mapping of the Sensor Interface Pins used for various supported interface formats.

Table 62. Camera Input Signal Cross Reference, Format, and Bits Per Cycle

Signal Name[1]	RGB565 8 bits 2 cycles	RGB565[2] 8 bits 3 cycles	RGB666[3] 8 bits 3 cycles	RGB888 8 bits 3 cycles	YCbCr[4] 8 bits 2 cycles	RGB565[5] 16 bits 1 cycle	YCbCr[6] 16 bits 1 cycle	YCbCr[7] 16 bits 1 cycle	YCbCr[8] 20 bits 1 cycle
IPUx_CSIx_ DATA00	—	—	—	—	—	—	—	0	C[0]
IPUx_CSIx_ DATA01	—	—	—	—	—	—	—	0	C[1]
IPUx_CSIx_ DATA02	—	—	—	—	—	—	—	C[0]	C[2]
IPUx_CSIx_ DATA03	—	—	—	—	—	—	—	C[1]	C[3]
IPUx_CSIx_ DATA04	—	—	—	—	—	B[0]	C[0]	C[2]	C[4]
IPU2_CSIx_ DATA_05	—	—	—	—	—	B[1]	C[1]	C[3]	C[5]
IPUx_CSIx_ DATA06	—	—	—	—	—	B[2]	C[2]	C[4]	C[6]
IPUx_CSIx_ DATA07	—	—	—	—	—	B[3]	C[3]	C[5]	C[7]
IPUx_CSIx_ DATA08	—	—	—	—	—	B[4]	C[4]	C[6]	C[8]
IPUx_CSIx_ DATA09	—	—	—	—	—	G[0]	C[5]	C[7]	C[9]
IPUx_CSIx_ DATA10	—	—	—	—	—	G[1]	C[6]	0	Y[0]
IPUx_CSIx_ DATA11	—	—	—	—	—	G[2]	C[7]	0	Y[1]
IPUx_CSIx_ DATA12	B[0], G[3]	R[2],G[4],B[2]	R/G/B[4]	R/G/B[0]	Y/C[0]	G[3]	Y[0]	Y[0]	Y[2]
IPUx_CSIx_ DATA13	B[1], G[4]	R[3],G[5],B[3]	R/G/B[5]	R/G/B[1]	Y/C[1]	G[4]	Y[1]	Y[1]	Y[3]
IPUx_CSIx_ DATA14	B[2], G[5]	R[4],G[0],B[4]	R/G/B[0]	R/G/B[2]	Y/C[2]	G[5]	Y[2]	Y[2]	Y[4]
IPUx_CSIx_ DATA15	B[3], R[0]	R[0],G[1],B[0]	R/G/B[1]	R/G/B[3]	Y/C[3]	R[0]	Y[3]	Y[3]	Y[5]
IPUx_CSIx_ DATA16	B[4], R[1]	R[1],G[2],B[1]	R/G/B[2]	R/G/B[4]	Y/C[4]	R[1]	Y[4]	Y[4]	Y[6]
IPUx_CSIx_ DATA17	G[0], R[2]	R[2],G[3],B[2]	R/G/B[3]	R/G/B[5]	Y/C[5]	R[2]	Y[5]	Y[5]	Y[7]
IPUx_CSIx_ DATA18	G[1], R[3]	R[3],G[4],B[3]	R/G/B[4]	R/G/B[6]	Y/C[6]	R[3]	Y[6]	Y[6]	Y[8]
IPUx_CSIx_ DATA19	G[2], R[4]	R[4],G[5],B[4]	R/G/B[5]	R/G/B[7]	Y/C[7]	R[4]	Y[7]	Y[7]	Y[9]

[1] IPU2_CSIx stands for IPU2_CSI1 or IPU2_CSI2.

Table 64. Video Signal Cross-Reference (continued)

i.MX 6DualPlus/6QuadPlus	LCD							Comment[1,2]
Port Name (x = 0, 1)	RGB, Signal Name (General)	RGB/TV Signal Allocation (Example)						
		16-bit RGB	18-bit RGB	24 Bit RGB	8-bit YCrCb[3]	16-bit YCrCb	20-bit YCrCb	
IPUx_DISPx_DAT05	DAT[5]	G[0]	B[5]	B[5]	Y/C[5]	C[5]	C[5]	—
IPUx_DISPx_DAT06	DAT[6]	G[1]	G[0]	B[6]	Y/C[6]	C[6]	C[6]	—
IPUx_DISPx_DAT07	DAT[7]	G[2]	G[1]	B[7]	Y/C[7]	C[7]	C[7]	—
IPUx_DISPx_DAT08	DAT[8]	G[3]	G[2]	G[0]	—	Y[0]	C[8]	—
IPUx_DISPx_DAT09	DAT[9]	G[4]	G[3]	G[1]	—	Y[1]	C[9]	—
IPUx_DISPx_DAT10	DAT[10]	G[5]	G[4]	G[2]	—	Y[2]	Y[0]	—
IPUx_DISPx_DAT11	DAT[11]	R[0]	G[5]	G[3]	—	Y[3]	Y[1]	—
IPUx_DISPx_DAT12	DAT[12]	R[1]	R[0]	G[4]	—	Y[4]	Y[2]	—
IPUx_DISPx_DAT13	DAT[13]	R[2]	R[1]	G[5]	—	Y[5]	Y[3]	—
IPUx_DISPx_DAT14	DAT[14]	R[3]	R[2]	G[6]	—	Y[6]	Y[4]	—
IPUx_DISPx_DAT15	DAT[15]	R[4]	R[3]	G[7]	—	Y[7]	Y[5]	—
IPUx_DISPx_DAT16	DAT[16]	—	R[4]	R[0]	—	—	Y[6]	—
IPUx_DISPx_DAT17	DAT[17]	—	R[5]	R[1]	—	—	Y[7]	—
IPUx_DISPx_DAT18	DAT[18]	—	—	R[2]	—	—	Y[8]	—
IPUx_DISPx_DAT19	DAT[19]	—	—	R[3]	—	—	Y[9]	—
IPUx_DISPx_DAT20	DAT[20]	—	—	R[4]	—	—	—	—
IPUx_DISPx_DAT21	DAT[21]	—	—	R[5]	—	—	—	—
IPUx_DISPx_DAT22	DAT[22]	—	—	R[6]	—	—	—	—
IPUx_DISPx_DAT23	DAT[23]	—	—	R[7]	—	—	—	—
IPUx_DIx_DISP_CLK	PixCLK							—
IPUx_DIx_PIN01	—							May be required for anti-tearing
IPUx_DIx_PIN02	HSYNC							—
IPUx_DIx_PIN03	VSYNC							VSYNC out

Table 85. SSI Receiver Timing with External Clock

ID	Parameter	Min	Max	Unit
External Clock Operation				
SS22	AUDx_TXC/AUDx_RXC clock period	81.4	—	ns
SS23	AUDx_TXC/AUDx_RXC clock high period	36	—	ns
SS24	AUDx_TXC/AUDx_RXC clock rise time	—	6.0	ns
SS25	AUDx_TXC/AUDx_RXC clock low period	36	—	ns
SS26	AUDx_TXC/AUDx_RXC clock fall time	—	6.0	ns
SS28	AUDx_RXC high to AUDx_TXFS (bl) high	–10	15.0	ns
SS30	AUDx_RXC high to AUDx_TXFS (bl) low	10	—	ns
SS32	AUDx_RXC high to AUDx_TXFS (wl) high	–10	15.0	ns
SS34	AUDx_RXC high to AUDx_TXFS (wl) low	10	—	ns
SS35	AUDx_TXC/AUDx_RXC External AUDx_TXFS rise time	—	6.0	ns
SS36	AUDx_TXC/AUDx_RXC External AUDx_TXFS fall time	—	6.0	ns
SS40	AUDx_RXD setup time before AUDx_RXC low	10	—	ns
SS41	AUDx_RXD hold time after AUDx_RXC low	2	—	ns

NOTE

- All the timings for the SSI are given for a non-inverted serial clock polarity (TSCKP/RSCKP = 0) and a non-inverted frame sync (TFSI/RFSI = 0). If the polarity of the clock and/or the frame sync have been inverted, all the timing remains valid by inverting the clock signal AUDx_TXC/AUDx_RXC and/or the frame sync AUDx_TXFS/AUDx_RXFS shown in the tables and in the figures.
- All timings are on Audiomux Pads when SSI is being used for data transfer.
- AUDx_TXC and AUDx_RXC refer to the Transmit and Receive sections of the SSI.
- The terms, WL and BL, refer to Word Length (WL) and Bit Length(BL).
- For internal Frame Sync operation using external clock, the frame sync timing is same as that of transmit data (for example, during AC97 mode of operation).

4.12.21 UART I/O Configuration and Timing Parameters

4.12.21.1 UART RS-232 I/O Configuration in Different Modes

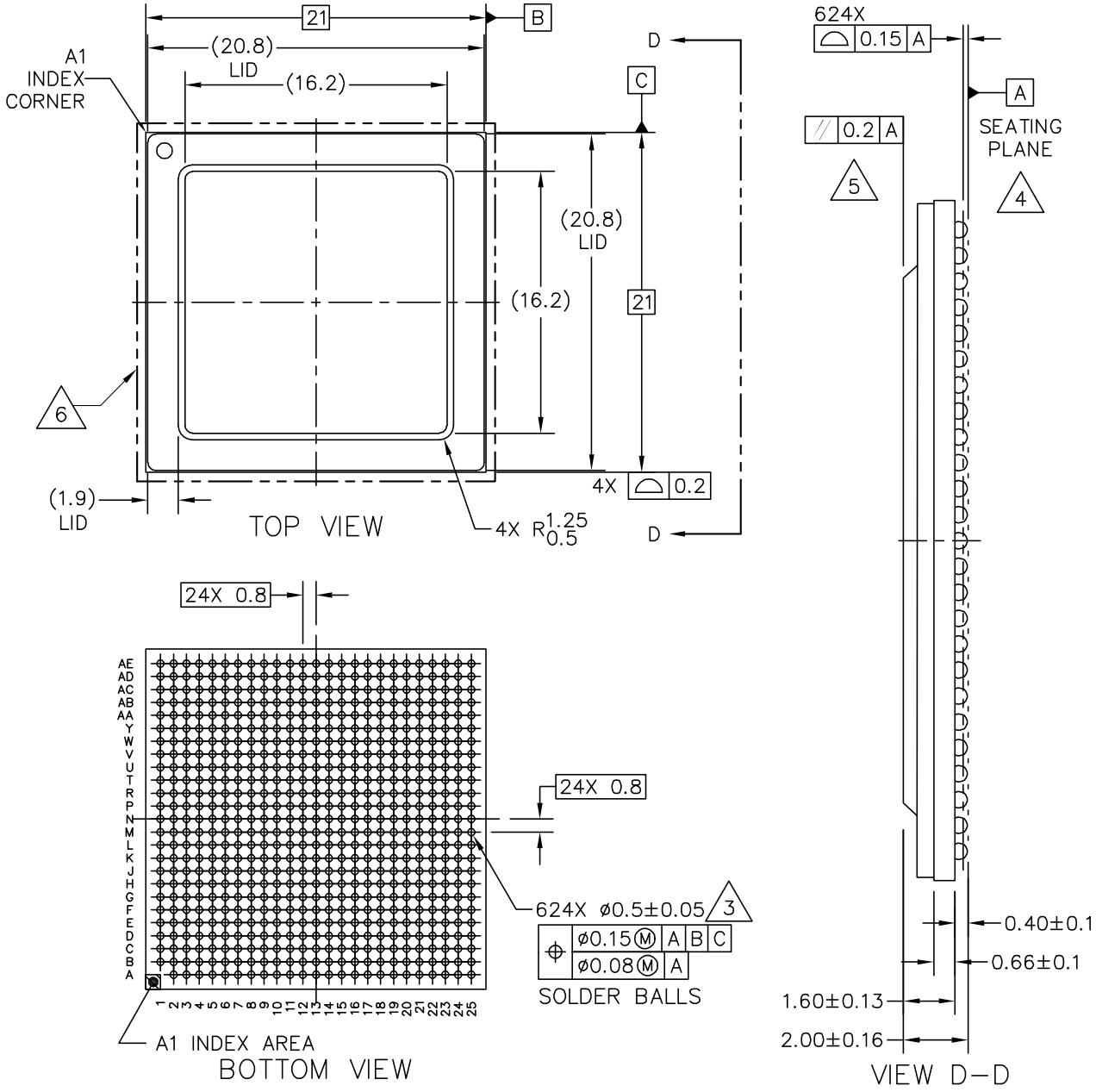
The i.MX 6DualPlus/6QuadPlus UART interfaces can serve both as DTE or DCE device. This can be configured by the DCEDTE control bit (default 0 – DCE mode). Table 86 shows the UART I/O configuration based on the enabled mode.

Table 86. UART I/O Configuration vs. Mode

Port	DTE Mode		DCE Mode	
	Direction	Description	Direction	Description
UARTx_RTS_B	Output	RTS from DTE to DCE	Input	RTS from DTE to DCE
UARTx_CTS_B	Input	CTS from DCE to DTE	Output	CTS from DCE to DTE
UARTx_DTR_B	Output	DTR from DTE to DCE	Input	DTR from DTE to DCE
UARTx_DSR_B	Input	DSR from DCE to DTE	Output	DSR from DCE to DTE
UARTx_DCD_B	Input	DCD from DCE to DTE	Output	DCD from DCE to DTE
UARTx_RI_B	Input	RING from DCE to DTE	Output	RING from DCE to DTE
UARTx_TX_DATA	Input	Serial data from DCE to DTE	Output	Serial data from DCE to DTE
UARTx_RX_DATA	Output	Serial data from DTE to DCE	Input	Serial data from DTE to DCE

6.2.1.1 21 x 21 mm Lidded Package

Figure 100 and Figure 101 show the top, bottom, and side views of the 21 × 21 mm lidded package.



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TITLE: 624 I/O FC PBGA, 21 X 21 X 2 PKG, 0.8 MM PITCH, STAMPED LID	DOCUMENT NO: 98ASA00330D	REV: E
	STANDARD: NON–JEDEC	
	SOT1643–1	07 JAN 2016

Figure 100. 21 x 21 mm Lidded Package Top, Bottom, and Side Views (Sheet 1 of 2)

Table 95. 21 x 21 mm Supplies Contact Assignment (continued)

Supply Rail Name	Ball(s) Position(s)	Remark
NVCC_MIPI	K7	Supply of the MIPI interface
NVCC_NANDF	G15	Supply of the RAW NAND Flash Memories interface
NVCC_PLL_OUT	E8	—
NVCC_RGMII	G18	Supply of the ENET interface
NVCC_SD1	G16	Supply of the SD card interface
NVCC_SD2	G17	Supply of the SD card interface
NVCC_SD3	G14	Supply of the SD card interface
PCIE_VP	H7	—
PCIE_REXT	A2	—
PCIE_VPH	G7	PCI PHY supply
PCIE_VPTX	G8	PCI PHY supply
SATA_REXT	C14	—
SATA_VP	G13	—
SATA_VPH	G12	—
USB_H1_VBUS	D10	—
USB_OTG_VBUS	E9	—
VDD_CACHE_CAP	N12	Cache supply input. This input should be connected to (driven by) VDD_SOC_CAP. The external capacitor used for VDD_SOC_CAP is sufficient for this supply.
VDD_FA	B5	—
VDD_SNVS_CAP	G9	Secondary supply for the SNVS (internal regulator output—requires capacitor if internal regulator is used)
VDD_SNVS_IN	G11	Primary supply for the SNVS regulator
VDDARM_CAP	H13, J13, K13, L13, M13, N13, P13, R13	Secondary supply for the ARM0 and ARM1 cores (internal regulator output—requires capacitor if internal regulator is used)
VDDARM_IN	H14, J14, K14, L14, M14, N14, P14, R14	Primary supply for the ARM0 and ARM1 core regulator
VDDARM23_CAP	H11, J11, K11, L11, M11, N11, P11, R11	Secondary supply for the ARM2 and ARM3 cores (internal regulator output—requires capacitor if internal regulator is used)
VDDARM23_IN	K9, L9, M9, N9, P9, R9, T9, U9	Primary supply for the ARM2 and ARM3 core regulator

Table 96. 21 x 21 mm Functional Contact Assignments (continued)

Ball Name	Ball	Power Group	Ball Type	Out of Reset Condition[1]			
				Default Mode (Reset Mode)	Default Function (Signal Name)	Input/Output	Value[2]
DRAM_D40	Y19	NVCC_DRAM	DDR	ALT0	DRAM_DATA40	Input	PU (100K)
DRAM_D41	AB20	NVCC_DRAM	DDR	ALT0	DRAM_DATA41	Input	PU (100K)
DRAM_D42	AB21	NVCC_DRAM	DDR	ALT0	DRAM_DATA42	Input	PU (100K)
DRAM_D43	AD21	NVCC_DRAM	DDR	ALT0	DRAM_DATA43	Input	PU (100K)
DRAM_D44	Y20	NVCC_DRAM	DDR	ALT0	DRAM_DATA44	Input	PU (100K)
DRAM_D45	AA20	NVCC_DRAM	DDR	ALT0	DRAM_DATA45	Input	PU (100K)
DRAM_D46	AE21	NVCC_DRAM	DDR	ALT0	DRAM_DATA46	Input	PU (100K)
DRAM_D47	AC21	NVCC_DRAM	DDR	ALT0	DRAM_DATA47	Input	PU (100K)
DRAM_D48	AC22	NVCC_DRAM	DDR	ALT0	DRAM_DATA48	Input	PU (100K)
DRAM_D49	AE22	NVCC_DRAM	DDR	ALT0	DRAM_DATA49	Input	PU (100K)
DRAM_D5	AD1	NVCC_DRAM	DDR	ALT0	DRAM_DATA05	Input	PU (100K)
DRAM_D50	AE24	NVCC_DRAM	DDR	ALT0	DRAM_DATA50	Input	PU (100K)
DRAM_D51	AC24	NVCC_DRAM	DDR	ALT0	DRAM_DATA51	Input	PU (100K)
DRAM_D52	AB22	NVCC_DRAM	DDR	ALT0	DRAM_DATA52	Input	PU (100K)
DRAM_D53	AC23	NVCC_DRAM	DDR	ALT0	DRAM_DATA53	Input	PU (100K)
DRAM_D54	AD25	NVCC_DRAM	DDR	ALT0	DRAM_DATA54	Input	PU (100K)
DRAM_D55	AC25	NVCC_DRAM	DDR	ALT0	DRAM_DATA55	Input	PU (100K)
DRAM_D56	AB25	NVCC_DRAM	DDR	ALT0	DRAM_DATA56	Input	PU (100K)
DRAM_D57	AA21	NVCC_DRAM	DDR	ALT0	DRAM_DATA57	Input	PU (100K)
DRAM_D58	Y25	NVCC_DRAM	DDR	ALT0	DRAM_DATA58	Input	PU (100K)
DRAM_D59	Y22	NVCC_DRAM	DDR	ALT0	DRAM_DATA59	Input	PU (100K)
DRAM_D6	AB4	NVCC_DRAM	DDR	ALT0	DRAM_DATA06	Input	PU (100K)
DRAM_D60	AB23	NVCC_DRAM	DDR	ALT0	DRAM_DATA60	Input	PU (100K)
DRAM_D61	AA23	NVCC_DRAM	DDR	ALT0	DRAM_DATA61	Input	PU (100K)
DRAM_D62	Y23	NVCC_DRAM	DDR	ALT0	DRAM_DATA62	Input	PU (100K)
DRAM_D63	W25	NVCC_DRAM	DDR	ALT0	DRAM_DATA63	Input	PU (100K)
DRAM_D7	AE4	NVCC_DRAM	DDR	ALT0	DRAM_DATA07	Input	PU (100K)
DRAM_D8	AD5	NVCC_DRAM	DDR	ALT0	DRAM_DATA08	Input	PU (100K)
DRAM_D9	AE5	NVCC_DRAM	DDR	ALT0	DRAM_DATA09	Input	PU (100K)
DRAM_DQM0	AC3	NVCC_DRAM	DDR	ALT0	DRAM_DQM0	Output	0
DRAM_DQM1	AC6	NVCC_DRAM	DDR	ALT0	DRAM_DQM1	Output	0
DRAM_DQM2	AB8	NVCC_DRAM	DDR	ALT0	DRAM_DQM2	Output	0
DRAM_DQM3	AE10	NVCC_DRAM	DDR	ALT0	DRAM_DQM3	Output	0
DRAM_DQM4	AB18	NVCC_DRAM	DDR	ALT0	DRAM_DQM4	Output	0
DRAM_DQM5	AC20	NVCC_DRAM	DDR	ALT0	DRAM_DQM5	Output	0
DRAM_DQM6	AD24	NVCC_DRAM	DDR	ALT0	DRAM_DQM6	Output	0

Table 96. 21 x 21 mm Functional Contact Assignments (continued)

Ball Name	Ball	Power Group	Ball Type	Out of Reset Condition[1]			
				Default Mode (Reset Mode)	Default Function (Signal Name)	Input/Output	Value[2]
DRAM_DQM7	Y21	NVCC_DRAM	DDR	ALT0	DRAM_DQM7	Output	0
DRAM_RAS	AB15	NVCC_DRAM	DDR	ALT0	DRAM_RAS_B	Output	0
DRAM_RESET	Y6	NVCC_DRAM	DDR	ALT0	DRAM_RESET	Output	0
DRAM_SDBA0	AC15	NVCC_DRAM	DDR	ALT0	DRAM_SDBA0	Output	0
DRAM_SDBA1	Y15	NVCC_DRAM	DDR	ALT0	DRAM_SDBA1	Output	0
DRAM_SDBA2	AB12	NVCC_DRAM	DDR	ALT0	DRAM_SDBA2	Output	0
DRAM_SDCKE0	Y11	NVCC_DRAM	DDR	ALT0	DRAM_SDCKE0	Output	0
DRAM_SDCKE1	AA11	NVCC_DRAM	DDR	ALT0	DRAM_SDCKE1	Output	0
DRAM_SDCLK_0	AD15	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDCLK0_P	Output	0
DRAM_SDCLK_0_B	AE15	NVCC_DRAM	DDRCLK	—	DRAM_SDCLK0_N	—	—
DRAM_SDCLK_1	AD14	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDCLK1_P	Output	0
DRAM_SDCLK_1_B	AE14	NVCC_DRAM	DDRCLK	—	DRAM_SDCLK1_N	—	—
DRAM_SDODT0	AC16	NVCC_DRAM	DDR	ALT0	DRAM_ODT0	Output	0
DRAM_SDODT1	AB17	NVCC_DRAM	DDR	ALT0	DRAM_ODT1	Output	0
DRAM_SDQS0	AE3	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDQS0_P	Input	Hi-Z
DRAM_SDQS0_B	AD3	NVCC_DRAM	DDRCLK	—	DRAM_SDQS0_N	—	—
DRAM_SDQS1	AD6	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDQS1_P	Input	Hi-Z
DRAM_SDQS1_B	AE6	NVCC_DRAM	DDRCLK	—	DRAM_SDQS1_N	—	—
DRAM_SDQS2	AD8	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDQS2_P	Input	Hi-Z
DRAM_SDQS2_B	AE8	NVCC_DRAM	DDRCLK	—	DRAM_SDQS2_N	—	—
DRAM_SDQS3	AC10	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDQS3_P	Input	Hi-Z
DRAM_SDQS3_B	AB10	NVCC_DRAM	DDRCLK	—	DRAM_SDQS3_N	—	—
DRAM_SDQS4	AD18	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDQS4_P	Input	Hi-Z
DRAM_SDQS4_B	AE18	NVCC_DRAM	DDRCLK	—	DRAM_SDQS4_N	—	—
DRAM_SDQS5	AD20	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDQS5_P	Input	Hi-Z
DRAM_SDQS5_B	AE20	NVCC_DRAM	DDRCLK	—	DRAM_SDQS5_N	—	—
DRAM_SDQS6	AD23	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDQS6_P	Input	Hi-Z
DRAM_SDQS6_B	AE23	NVCC_DRAM	DDRCLK	—	DRAM_SDQS6_N	—	—
DRAM_SDQS7	AA25	NVCC_DRAM	DDRCLK	ALT0	DRAM_SDQS7_P	Input	Hi-Z
DRAM_SDQS7_B	AA24	NVCC_DRAM	DDRCLK	—	DRAM_SDQS7_N	—	—
DRAM_SDWE	AB16	NVCC_DRAM	DDR	ALT0	DRAM_SDWE_B	Output	0
DSI_CLK0M	H3	NVCC_MIPI	—	—	DSI_CLK_N	—	—
DSI_CLK0P	H4	NVCC_MIPI	—	—	DSI_CLK_P	—	—
DSI_D0M	G2	NVCC_MIPI	—	—	DSI_DATA0_N	—	—
DSI_D0P	G1	NVCC_MIPI	—	—	DSI_DATA0_P	—	—
DSI_D1M	H2	NVCC_MIPI	—	—	DSI_DATA1_N	—	—

Table 96. 21 x 21 mm Functional Contact Assignments (continued)

Ball Name	Ball	Power Group	Ball Type	Out of Reset Condition[1]			
				Default Mode (Reset Mode)	Default Function (Signal Name)	Input/Output	Value[2]
NANDF_WP_B	E15	NVCC_NANDF	GPIO	ALT5	GPIO6_IO09	Input	PU (100K)
ONOFF	D12	VDD_SNVS_IN	GPIO	—	SRC_ONOFF	Input	PU (100K)
PCIE_RXM	B1	PCIE_VPH	—	—	PCIE_RX_N	—	—
PCIE_RXP	B2	PCIE_VPH	—	—	PCIE_RX_P	—	—
PCIE_TXM	A3	PCIE_VPH	—	—	PCIE_TX_N	—	—
PCIE_TXP	B3	PCIE_VPH	—	—	PCIE_TX_P	—	—
PMIC_ON_REQ	D11	VDD_SNVS_IN	GPIO	ALT0	SNVS_PMIC_ON_REQ	Output	Open Drain with PU (100K)
PMIC_STBY_REQ	F11	VDD_SNVS_IN	GPIO	ALT0	CCM_PMIC_STBY_REQ	Output	0
POR_B	C11	VDD_SNVS_IN	GPIO	ALT0	SRC_POR_B	Input	PU (100K)
RGMII_RD0	C24	NVCC_RGMII	DDR	ALT5	GPIO6_IO25	Input	PU (100K)
RGMII_RD1	B23	NVCC_RGMII	DDR	ALT5	GPIO6_IO27	Input	PU (100K)
RGMII_RD2	B24	NVCC_RGMII	DDR	ALT5	GPIO6_IO28	Input	PU (100K)
RGMII_RD3	D23	NVCC_RGMII	DDR	ALT5	GPIO6_IO29	Input	PU (100K)
RGMII_RX_CTL	D22	NVCC_RGMII	DDR	ALT5	GPIO6_IO24	Input	PD (100K)
RGMII_RXC	B25	NVCC_RGMII	DDR	ALT5	GPIO6_IO30	Input	PD (100K)
RGMII_TD0	C22	NVCC_RGMII	DDR	ALT5	GPIO6_IO20	Input	PU (100K)
RGMII_TD1	F20	NVCC_RGMII	DDR	ALT5	GPIO6_IO21	Input	PU (100K)
RGMII_TD2	E21	NVCC_RGMII	DDR	ALT5	GPIO6_IO22	Input	PU (100K)
RGMII_TD3	A24	NVCC_RGMII	DDR	ALT5	GPIO6_IO23	Input	PU (100K)
RGMII_TX_CTL	C23	NVCC_RGMII	DDR	ALT5	GPIO6_IO26	Input	PD (100K)
RGMII_TXC	D21	NVCC_RGMII	DDR	ALT5	GPIO6_IO19	Input	PD (100K)
RTC_XTALI	D9	VDD_SNVS_CAP	—	—	RTC_XTALI	—	—
RTC_XTALO	C9	VDD_SNVS_CAP	—	—	RTC_XTALO	—	—
SATA_RXM	A14	SATA_VPH	—	—	SATA_PHY_RX_N	—	—
SATA_RXP	B14	SATA_VPH	—	—	SATA_PHY_RX_P	—	—
SATA_TXM	B12	SATA_VPH	—	—	SATA_PHY_TX_N	—	—
SATA_TXP	A12	SATA_VPH	—	—	SATA_PHY_TX_P	—	—
SD1_CLK	D20	NVCC_SD1	GPIO	ALT5	GPIO1_IO20	Input	PU (100K)
SD1_CMD	B21	NVCC_SD1	GPIO	ALT5	GPIO1_IO18	Input	PU (100K)
SD1_DAT0	A21	NVCC_SD1	GPIO	ALT5	GPIO1_IO16	Input	PU (100K)
SD1_DAT1	C20	NVCC_SD1	GPIO	ALT5	GPIO1_IO17	Input	PU (100K)
SD1_DAT2	E19	NVCC_SD1	GPIO	ALT5	GPIO1_IO19	Input	PU (100K)
SD1_DAT3	F18	NVCC_SD1	GPIO	ALT5	GPIO1_IO21	Input	PU (100K)
SD2_CLK	C21	NVCC_SD2	GPIO	ALT5	GPIO1_IO10	Input	PU (100K)
SD2_CMD	F19	NVCC_SD2	GPIO	ALT5	GPIO1_IO11	Input	PU (100K)

[2] Variance of the pull-up and pull-down strengths are shown in the tables as follows:
- Table 22, “GPIO I/O DC Parameters,” on page 40.
- Table 24, “LPDDR2 I/O DC Electrical Parameters,” on page 42.
- Table 25, “DDR3/DDR3L I/O DC Electrical Parameters,” on page 42.

[3] ENET_REF_CLK is used as a clock source for MII and RGMII modes only. RMII mode uses either GPIO_16 or RGMII_TX_CTL as a clock source. For more information on these clocks, see your specific device reference manual and the *Hardware Development Guide for i.MX 6Quad, 6Dual, 6DualLite, 6Solo Families of Applications Processors* (IMX6DQ6SDLHDG).

6.2.4 Signals with Different Reset States

For most of the signals, the state during reset is same as the state after reset, given in Out of Reset Condition column of Table 96, “21 x 21 mm Functional Contact Assignments”. However, there are few signals for which the state during reset is different from the state after reset. These signals along with their state during reset are given in Table 97.

Table 97. Signals with Differing Before Reset and After Reset States

Ball Name	Before Reset State	
	Input/Output	Value
EIM_A16	Input	PD (100K)
EIM_A17	Input	PD (100K)
EIM_A18	Input	PD (100K)
EIM_A19	Input	PD (100K)
EIM_A20	Input	PD (100K)
EIM_A21	Input	PD (100K)
EIM_A22	Input	PD (100K)
EIM_A23	Input	PD (100K)
EIM_A24	Input	PD (100K)
EIM_A25	Input	PD (100K)
EIM_DA0	Input	PD (100K)
EIM_DA1	Input	PD (100K)
EIM_DA2	Input	PD (100K)
EIM_DA3	Input	PD (100K)
EIM_DA4	Input	PD (100K)
EIM_DA5	Input	PD (100K)
EIM_DA6	Input	PD (100K)
EIM_DA7	Input	PD (100K)
EIM_DA8	Input	PD (100K)
EIM_DA9	Input	PD (100K)
EIM_DA10	Input	PD (100K)
EIM_DA11	Input	PD (100K)
EIM_DA12	Input	PD (100K)
EIM_DA13	Input	PD (100K)

6.2.5 21 x 21 mm, 0.8 mm Pitch Ball Map

Table 98 shows the FCPBGA 21 x 21 mm, 0.8 mm pitch ball map.

Table 98. 21 x 21 mm, 0.8 mm Pitch Ball Map

	A	B	C	D	E	F	G
1		PCIE_RXM	GND	CSI_D1M	CSI_D2M	CSI_D3P	DSI_D0P
2	PCIE_REXT	PCIE_RXP	JTAG_TRSTB	CSI_D1P	CSI_D2P	CSI_D3M	DSI_D0M
3	PCIE_TXM	PCIE_TXP	JTAG_TMS	GND	CSI_D0P	CSI_CLK0P	GND
4	GND	GND	GND	CSI_REXT	CSI_D0M	CSI_CLK0M	DSI_REXT
5	FA_ANA	VDD_FA	CLK2_N	CLK2_P	GND	GND	JTAG_TDI
6	USB_OTG_DP	USB_OTG_DN	GND	GND	GND	GND	JTAG_TDO
7	XTALI	XTALO	CLK1_N	CLK1_P	GND	GND	PCIE_VPH
8	GND	USB_OTG_CHD_B	GPANAIO	GND	NVCC_PLL_OUT	GND	PCIE_VPTX
9	MLB_SN	MLB_SP	RTC_XTALO	RTC_XTALI	USB_OTG_VBUS	VDDUSB_CAP	VDD_SNVS_CAP
10	MLB_DP	MLB_DN	GND	USB_H1_VBUS	USB_H1_DP	USB_H1_DN	GND
11	MLB_CN	MLB_CP	POR_B	PMIC_ON_REQ	TAMPER	PMIC_STBY_REQ	VDD_SNVS_IN
12	SATA_TXP	SATA_TXM	BOOT_MODE0	ONOFF	TEST_MODE	BOOT_MODE1	SATA_VPH
13	GND	SD3_CMD	SD3_DAT5	SD3_DAT4	SD3_DAT6	SD3_DAT7	SATA_VP
14	SATA_RXM	SATA_RXP	SATA_REXT	SD3_CLK	SD3_DAT0	SD3_DAT1	NVCC_SD3
15	SD3_DAT2	SD3_DAT3	NANDF_CLE	SD3_RST	NANDF_WP_B	NANDF_CS0	NVCC_NANDF
16	NANDF_ALE	NANDF_RB0	NANDF_CS1	NANDF_CS3	SD4_CLK	NANDF_D2	NVCC_SD1
17	NANDF_CS2	SD4_CMD	NANDF_D1	NANDF_D3	NANDF_D6	SD4_DAT2	NVCC_SD2
18	NANDF_D0	NANDF_D5	NANDF_D7	SD4_DAT0	SD4_DAT4	SD1_DAT3	NVCC_RGMII
19	NANDF_D4	SD4_DAT1	SD4_DAT5	SD4_DAT7	SD1_DAT2	SD2_CMD	GND
20	SD4_DAT3	SD4_DAT6	SD1_DAT1	SD1_CLK	SD2_DAT1	RGMII_TD1	EIM_D20
21	SD1_DAT0	SD1_CMD	SD2_CLK	RGMII_TXC	RGMII_TD2	EIM_D17	EIM_D19
22	SD2_DAT0	SD2_DAT3	RGMII_TD0	RGMII_RX_CTL	EIM_EB2	EIM_D24	EIM_D25
23	SD2_DAT2	RGMII_RD1	RGMII_TX_CTL	RGMII_RD3	EIM_D22	EIM_EB3	EIM_D28
24	RGMII_TD3	RGMII_RD2	RGMII_RD0	EIM_D18	EIM_D26	EIM_A22	EIM_A17
25	GND	RGMII_RXC	EIM_D16	EIM_D23	EIM_D27	EIM_A24	EIM_A19

Table 99. i.MX 6DualPlus/6QuadPlus Data Sheet Document Revision History (continued)

Rev. Number	Date	Substantive Change(s)
2 *(Cont.)*	09/2017	• Section 4.6.4, "RGMII I/O 2.5V I/O DC Electrical Parameters" on page 41: Added section and table. • Section 4.10, "Multi-Mode DDR Controller (MMDC)" on page 64: Replaced section with new content. Was 4.9.4 "*DDR SDRAM Specific Parameters (DDR3/DDR3L/LPDDR2)*" with timing diagrams and parameter tables for DDR. • Table 51, "eMMC4.4/4.41 Interface Timing Specification," on page 81: – Corrected SD3, uSDHC Input Setup Time, minimum value from 2.6ns to 1.7ns. – Added footnote to Card Input Clock regarding duty cycle range. • Table 52, "SDR50/SDR104 Interface Timing Specification," on page 82: Changes to Min/Max values: – SD2 min from: 0.3 x tCLK; to: 0.46 x tCLK – SD2 max from: 0.7 x tCLK to: 0.54 x tCLK – SD3 min from: 0.3 x tCLK; to: 0.46 x tCLK. Also corrected ID from duplicate SD2 to SD3. – SD3 max from: 0.7 x tCLK; to: 0.54 x tCLK – SD5 max from: 1 ns; to: 0.74 ns • Table 62, "Camera Input Signal Cross Reference, Format, and Bits Per Cycle," on page 95: Changed RGB565, 16 bits column heading from 2 cycles to 1 cycle. • Table 95, "21 x 21 mm Supplies Contact Assignment," on page 144: – Added description to ZQPAD. – Added description to GPANAIO row: "…output for NXP use only…" • Table 96, "21 x 21 mm Functional Contact Assignments," on page 146: – Changed DRAM_SDCLK_0,DRAM_SDCLK_1 from *"Input–Hi-Z"* to *"Output–*0". • Section 6.2.1.1, "21 x 21 mm Lidded Package" on page 142: Added section.
1	3/2016	Revision 1 changes are within Table 20, "Maximum Supply Currents" on page 48 Changed: • VDD-ARM_IN with condition 996 MHz, CoreMark maximum current value from 1500 to 1200 VDD-ARM_IN with condition 852 MHz, CoreMark maximum current value from 1360 to 1090 • Added footnote regarding values are assumed when VDD_ARM23_IN and VDD_ARM23_CAP are connected to ground.

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